

Silicon Carbide Power Schottky Diode

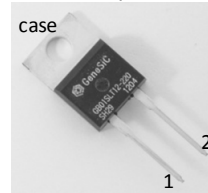
V_{RRM}	=	1200 V
$I_F (T_C = 25^\circ\text{C})$	=	2.5 A
Q_C	=	7 nC

Features

- 1200 V Schottky rectifier
- 175 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F

Package

- RoHS Compliant


TO – 220AC


Advantages

- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
- Low reverse leakage current at operating temperature

Applications

- Power Factor Correction (PFC)
- Switched-Mode Power Supply (SMPS)
- Solar Inverters
- Wind Turbine Inverters
- Motor Drives
- Induction Heating
- Uninterruptible Power Supply (UPS)
- High Voltage Multipliers

Maximum Ratings at $T_j = 175^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current	I_F	$T_C \leq 160^\circ\text{C}$	1	A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 160^\circ\text{C}$	2	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$	10	A
		$T_C = 160^\circ\text{C}, t_p = 10\text{ ms}$	8	A
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ }\mu\text{s}$	65	A
i^2t value	$\int i^2 dt$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$	0.5	A^2s
		$T_C = 160^\circ\text{C}, t_p = 10\text{ ms}$	0.3	A^2s
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$	42	W
Operating and storage temperature	T_j, T_{stg}		-55 to 175	$^\circ\text{C}$

Electrical Characteristics at $T_j = 175^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 1\text{ A}, T_j = 25^\circ\text{C}$		1.6	1.8	V
		$I_F = 1\text{ A}, T_j = 175^\circ\text{C}$		2.4	3.7	
Reverse current	I_R	$V_R = 1200\text{ V}, T_j = 25^\circ\text{C}$		1	10	μA
		$V_R = 1200\text{ V}, T_j = 175^\circ\text{C}$		10	100	
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 175^\circ\text{C}$	$V_R = 400\text{ V}$	7		nC
	$V_R = 960\text{ V}$		13			
Switching time	t_s	$V_R = 1\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$	$V_R = 400\text{ V}$	< 17		ns
			$V_R = 960\text{ V}$			
Total capacitance	C	$V_R = 1\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		69		pF
		$V_R = 400\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		10		
		$V_R = 1000\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		8		

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	3.6	$^\circ\text{C}/\text{W}$
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Mechanical Properties

Mounting torque	M	0.6	Nm
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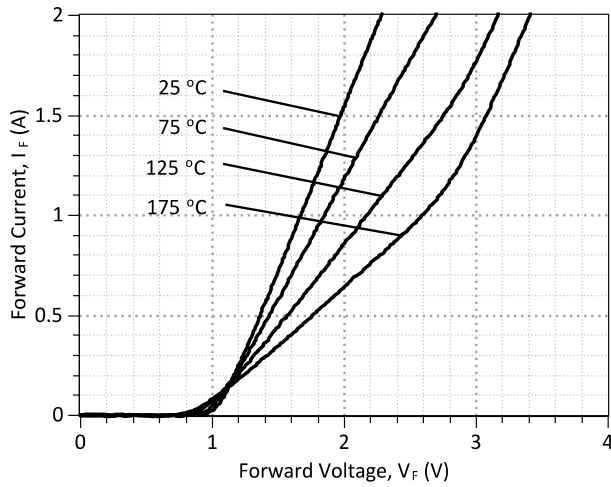


Figure 1: Typical Forward Characteristics

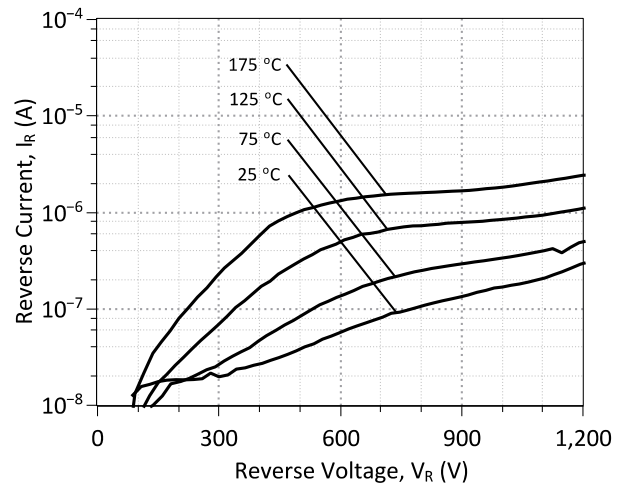


Figure 2: Typical Reverse Characteristics

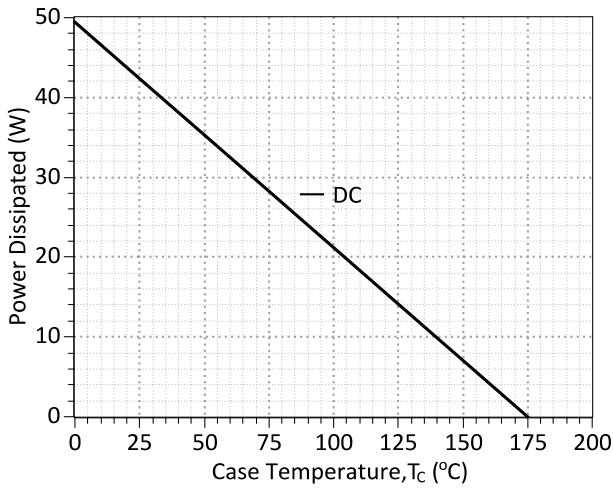
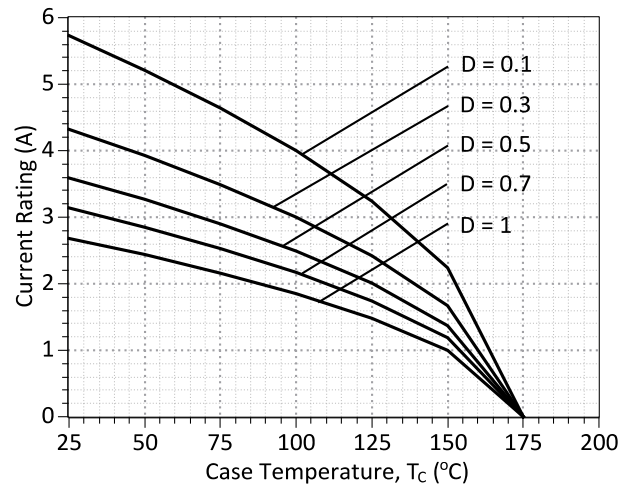


Figure 3: Power Derating Curve



**Figure 4: Current Derating Curves (D = t_p/T, t_p = 400 μs)
(Considering worst case Z_{th} conditions)**

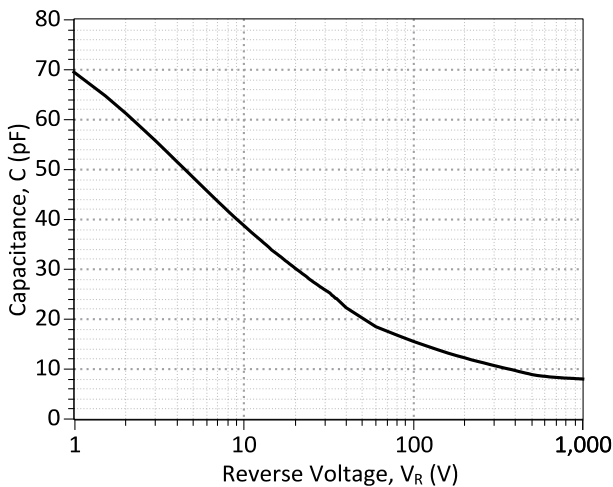


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

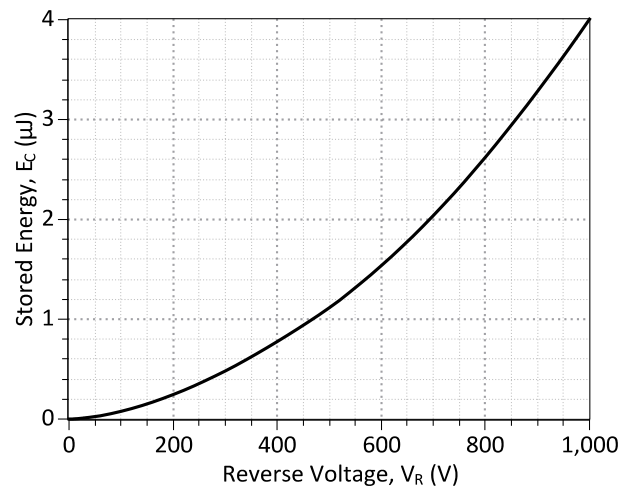


Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics

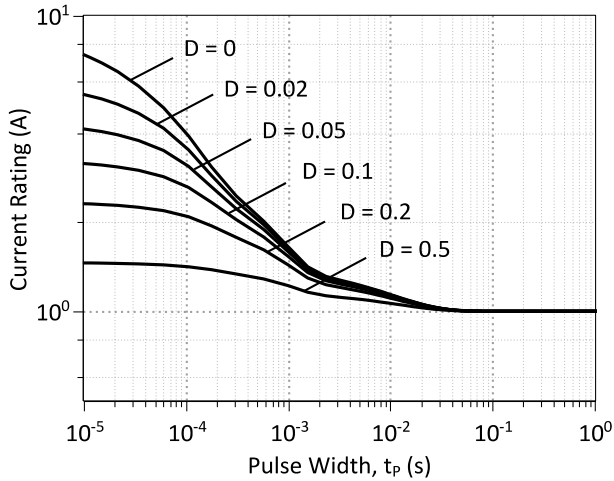


Figure 7: Current vs Pulse Duration Curves at $T_c = 160\text{ }^\circ\text{C}$

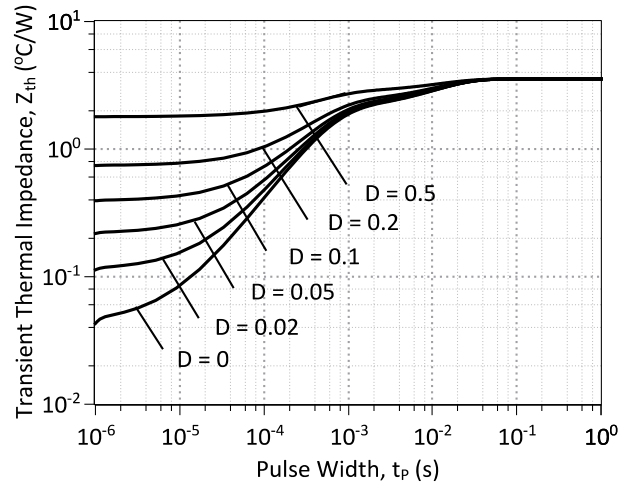
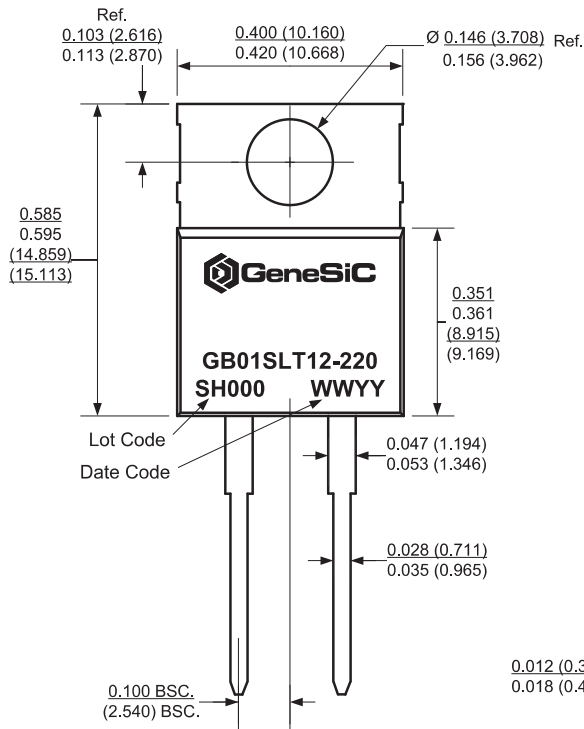


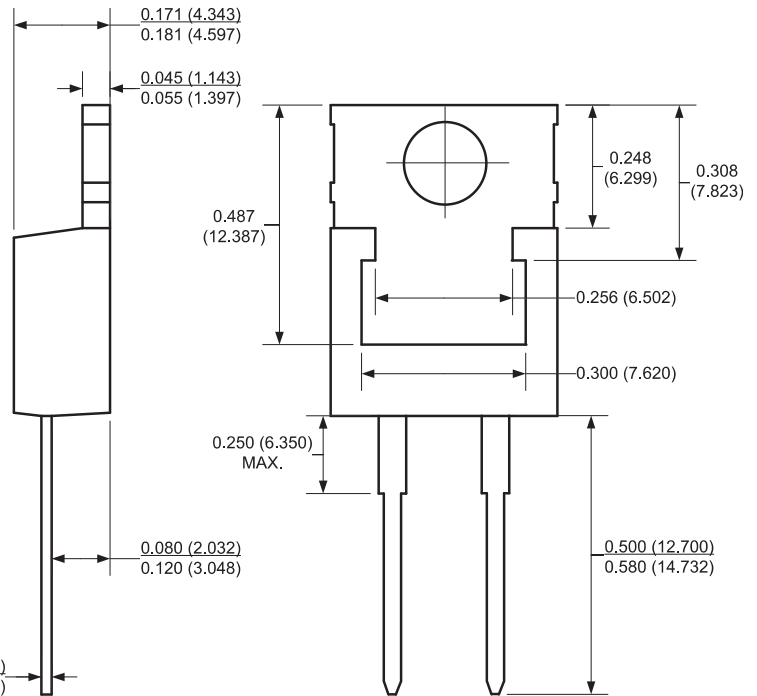
Figure 8: Transient Thermal Impedance

Package Dimensions:

TO-220AC



PACKAGE OUTLINE



NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History			
Date	Revision	Comments	Supersedes
2014/08/26	3	Updated Electrical Characteristics	
2013/02/05	2	Second generation update	
2012/05/22	1	Second generation release	
2010/12/13	0	Initial release	

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GB01SLT12-220 device.

```
*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      04-SEP-2013   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*      http://www.genesicsemi.com/index.php/sic-products/schottky
*
*      COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
*      ALL RIGHTS RESERVED
*
*      These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
*      OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
*      TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
*      PARTICULAR PURPOSE."
*      Models accurate up to 2 times rated drain current.
*
*      Start of GB01SLT12-220 SPICE Model
*
.SUBCKT GB01SLT12 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0069); Temperature Dependant Resistor
D1 INT KATHODE GB01SLT12_25C; Call the 25C Diode Model
D2 ANODE KATHODE GB01SLT12_PIN; Call the PiN Diode Model
.MODEL GB01SLT12_25C D
+ IS      7.27E-19      RS      0.592251
+ N       1            IKF     407.773
+ EG     1.2           XTI     3
+ CJO    7.90E-11     VJ      0.367
+ M      1.63          FC      0.5
+ TT     1.00E-10     BV      1200
+ IBV    1.00E-03     VPK     1200
+ IAVE   1            TYPE    SiC_Schottky
+ MFG    GeneSiC_Semiconductor
.MODEL GB01SLT12_PIN D
+ IS      1.08E-17     RS      1.8
+ N       2.2313      IKF     999
+ EG     3.23         XTI     -65
+ FC     0.5          TT      0
+ BV     1200         IBV     1.00E-03
+ VPK    1200         IAVE    1
+ TYPE   SiC_PiN
.ENDS
*
*      End of GB01SLT12-220 SPICE Model
```